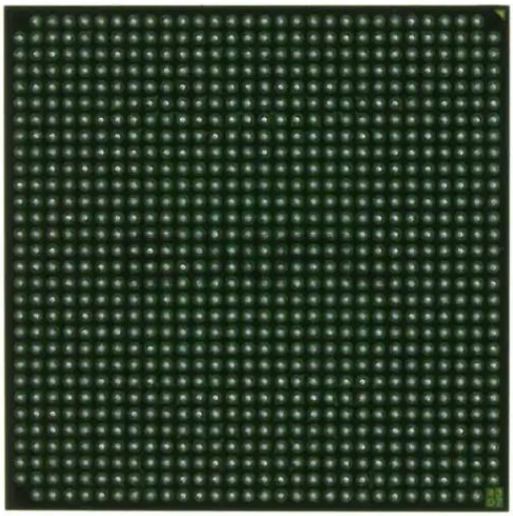

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2688
Number of Logic Elements/Cells	-
Total RAM Bits	1032192
Number of I/O	624
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2v2000-4ffg896c

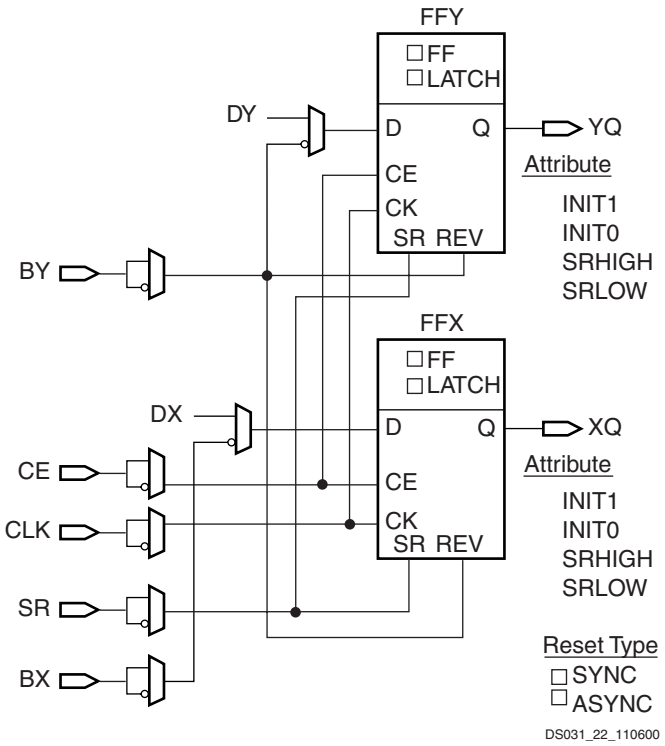


Figure 17: **Register / Latch Configuration in a Slice**

The set and reset functionality of a register or a latch can be configured as follows:

- No set or reset
- Synchronous set
- Synchronous reset
- Synchronous set and reset
- Asynchronous set (preset)
- Asynchronous reset (clear)
- Asynchronous set and reset (preset and clear)

The synchronous reset has precedence over a set, and an asynchronous clear has precedence over a preset.

Distributed SelectRAM Memory

Each function generator (LUT) can implement a 16 x 1-bit synchronous RAM resource called a distributed SelectRAM element. The SelectRAM elements are configurable within a CLB to implement the following:

- Single-Port 16 x 8 bit RAM
- Single-Port 32 x 4 bit RAM
- Single-Port 64 x 2 bit RAM
- Single-Port 128 x 1 bit RAM
- Dual-Port 16 x 4 bit RAM
- Dual-Port 32 x 2 bit RAM
- Dual-Port 64 x 1 bit RAM

Distributed SelectRAM memory modules are synchronous (write) resources. The combinatorial read access time is extremely fast, while the synchronous write simplifies high-speed designs. A synchronous read can be implemented with a storage element in the same slice. The distributed SelectRAM memory and the storage element share the same clock input. A Write Enable (WE) input is active High, and is driven by the SR input.

Table 9 shows the number of LUTs (2 per slice) occupied by each distributed SelectRAM configuration.

Table 9: **Distributed SelectRAM Configurations**

RAM	Number of LUTs
16 x 1S	1
16 x 1D	2
32 x 1S	2
32 x 1D	4
64 x 1S	4
64 x 1D	8
128 x 1S	8

Notes:
1. S = single-port configuration; D = dual-port configuration

For single-port configurations, distributed SelectRAM memory has one address port for synchronous writes and asynchronous reads.

For dual-port configurations, distributed SelectRAM memory has one port for synchronous writes and asynchronous reads and another port for asynchronous reads. The function generator (LUT) has separated read address inputs (A1, A2, A3, A4) and write address inputs (WG1/WF1, WG2/WF2, WG3/WF3, WG4/WF4).

In single-port mode, read and write addresses share the same address bus. In dual-port mode, one function generator (R/W port) is connected with shared read and write addresses. The second function generator has the A inputs (read) connected to the second read-only port address and the W inputs (write) shared with the first read/write port address.

The Virtex-II implementation process is comprised of Synthesis, translation, mapping, place and route, and configuration file generation. While the tools can be run individually, many designers choose to run the entire implementation process with the click of a button. To assist those who prefer to script their design flows, Xilinx provides Xflow, an automated single command line process.

Design Verification

In addition to conventional design verification using static timing analysis or simulation techniques, Xilinx offers powerful in-circuit debugging techniques using ChipScope ILA (Integrated Logic Analysis). The reconfigurable nature of Xilinx FPGAs means that designs can be verified in real time without the need for extensive sets of software simulation vectors.

For simulation, the system extracts post-layout timing information from the design database, and back-annotates this information into the netlist for use by the simulator. The back annotation features a variety of patented Xilinx techniques, resulting in the industry's most powerful simulation flows. Alternatively, timing-critical portions of a design can be verified using the Xilinx static timing analyzer or a third party static timing analysis tool like Synopsys Prime Time™, by exporting timing data in the STAMP data format.

For in-circuit debugging, ChipScope ILA enables designers to analyze the real-time behavior of a device while operating at full system speeds. Logic analysis commands and captured data are transferred between the ChipScope software and ILA cores within the Virtex-II FPGA, using industry standard JTAG protocols. These JTAG transactions are driven over an optional download cable (MultiLINX or JTAG), connecting the Virtex device in the target system to a PC or workstation.

ChipScope ILA was designed to look and feel like a logic analyzer, making it easy to begin debugging a design immediately. Modifications to the desired logic analysis can be downloaded directly into the system in a matter of minutes.

Other Unique Features of Virtex-II Design Flow

Xilinx design flows feature a number of unique capabilities. Among these are efficient incremental HDL design flows; a robust capability that is enabled by Xilinx exclusive hierarchical floorplanning capabilities. Another powerful design capability only available in the Xilinx design flow is "Modular Design", part of the Xilinx suite of team design tools, which enables autonomous design, implementation, and verification of design modules.

Incremental Synthesis

Xilinx unique hierarchical floorplanning capabilities enable designers to create a programmable logic design by isolating design changes within one hierarchical "logic block", and perform synthesis, verification and implementation processes on that specific logic block. By preserving the logic in unchanged portions of a design, Xilinx incremental design makes the high-density design process more efficient.

Xilinx hierarchical floorplanning capabilities can be specified using the high-level floorplanner or a preferred RTL floorplanner (see the Xilinx web site for a list of supported EDA partners). When used in conjunction with one of the EDA partners' floorplanners, higher performance results can be achieved, as many synthesis tools use this more predictable detailed physical implementation information to establish more aggressive and accurate timing estimates when performing their logic optimizations.

Modular Design

Xilinx innovative modular design capabilities take the incremental design process one step further by enabling the designer to delegate responsibility for completing the design, synthesis, verification, and implementation of a hierarchical "logic block" to an arbitrary number of designers - assigning a specific region within the target FPGA for exclusive use by each of the team members.

This team design capability enables an autonomous approach to design modules, changing the hand-off point to the lead designer or integrator from "my module works in simulation" to "my module works in the FPGA". This unique design methodology also leverages the Xilinx hierarchical floorplanning capabilities and enables the Xilinx (or EDA partner) floorplanner to manage the efficient implementation of very high-density FPGAs.

Date	Version	Revision
07/16/02	2.0	• Updated compatible input standards listed in Table 6.
09/26/02	2.1	• Changed number of resources available to the XC2V40 device in Table 13. • Clarified Power On Reset information under Configuration Sequence.
12/06/02	2.1.1	• Cosmetic edits.
05/07/03	2.1.2	• Added qualification note to Figure 13, page 11. • Corrected sentence in section Input/Output Individual Options, page 4, to read “The optional weak-keeper circuit is connected to each *user I/O pad*.” • Corrected typographical errors in Table 3 for names of HSTL_[x]_DCI_18 standards.
06/19/03	2.2	• Removed Compatible Output Standards and Compatible Input Standards tables. • Added new Table 5, Summary of Voltage Supply Requirements for All Input and Output Standards. This table replaces deleted I/O standards tables. • Added section Rules for Combining I/O Standards in the Same Bank, page 6.
08/01/03	3.0	All Virtex-II devices and speed grades now Production. See Table 13, Module 3.
10/14/03	3.1	• Added section Local Clocking, page 29. • Table 1, page 1: - Added SSTL18_I and SSTL18_II. - Corrected names of 1.8V HSTL_I-IV standards to “HSTL_I-IV_18”. - Corrected Input V_{REF} for HSTL_III-IV_18 from 1.08V to 1.1V. - Changed “N/A” to “N/R” (no requirement). • Table 2, page 2: - Changed “N/A” to “N/R” (no requirement). • Table 3, page 2: - Added SSTL18_I_DCI, SSTL18_II_DCI, LVDS_33_DCI, LVDSEXT_33_DCI, LVDS_25_DCI, and LVDSEXT_25_DCI. - Corrected Input V_{REF} for HSTL_III-IV_18 from 1.08V to 1.1V. • Sections Slave-Serial Mode and Master-Serial Mode, page 36: Changed "rising" to "falling" edge with respect to DOUT. • Added verbiage to section Bitstream Encryption, page 38: “For devices that support this feature, please contact your sales representative for specific ordering part number.”
03/29/04	3.2	• Table 2, page 2, and Table 5, page 7: Removed LVDS_33_DCI and LVDSEXT_33_DCI from tables. • Table 26, page 37: Updated bitstream lengths. • Section BUFGMUX, page 29: Corrected the definition of the "presently selected clock" to be I0 or I1. Corrected signal names in Figure 44 and associated text from CLK0 and CLK1 to I0 and I1. • Recompiled for backward compatibility with Acrobat 4 and above.
06/24/04	3.3	• Table 1, page 1: Added example to Footnote (1) regarding V_{CCO} rules for GTL and GTLP. • Added reference to Pb-free package types in Figure 7, page 6.
03/01/05	3.4	• Reassigned heading hierarchies for better agreement with content. • Table 2: Corrected V_{OD} output voltages. • Table 26: Updated bitstream lengths.
11/05/07	3.5	• Updated copyright statement and legal disclaimer. • Boundary-Scan (JTAG, IEEE 1532) Mode, page 37: Updated IEEE 1149.1 compliance statement.

Table 17: **IOB Output Switching Characteristics Standard Adjustments *(Continued)***

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-6	-5	-4	
LVCMOS, 2.5V, Fast, 16 mA	LVCMOS25_F16	$T_{OLVCMOS25\_F16}$	–0.18	–0.19	–0.21	ns
LVCMOS, 2.5V, Fast, 24 mA	LVCMOS25_F24	$T_{OLVCMOS25\_F24}$	–0.35	–0.36	–0.40	ns
LVCMOS, 1.8V, Slow, 2 mA	LVCMOS18_S2	$T_{OLVCMOS18\_S2}$	15.62	16.10	17.71	ns
LVCMOS, 1.8V, Slow, 4 mA	LVCMOS18_S4	$T_{OLVCMOS18\_S4}$	10.20	10.51	11.57	ns
LVCMOS, 1.8V, Slow, 6 mA	LVCMOS18_S6	$T_{OLVCMOS18\_S6}$	7.52	7.75	8.53	ns
LVCMOS, 1.8V, Slow, 8 mA	LVCMOS18_S8	$T_{OLVCMOS18\_S8}$	6.87	7.08	7.78	ns
LVCMOS, 1.8V, Slow, 12 mA	LVCMOS18_S12	$T_{OLVCMOS18\_S12}$	5.54	5.71	6.28	ns
LVCMOS, 1.8V, Slow, 16 mA	LVCMOS18_S16	$T_{OLVCMOS18\_S16}$	5.31	5.47	6.02	ns
LVCMOS, 1.8V, Fast, 2 mA	LVCMOS18_F2	$T_{OLVCMOS18\_F2}$	5.55	5.72	6.30	ns
LVCMOS, 1.8V, Fast, 4 mA	LVCMOS18_F4	$T_{OLVCMOS18\_F4}$	1.89	1.95	2.15	ns
LVCMOS, 1.8V, Fast, 6 mA	LVCMOS18_F6	$T_{OLVCMOS18\_F6}$	0.83	0.85	0.94	ns
LVCMOS, 1.8V, Fast, 8 mA	LVCMOS18_F8	$T_{OLVCMOS18\_F8}$	0.70	0.72	0.80	ns
LVCMOS, 1.8V, Fast, 12 mA	LVCMOS18_F12	$T_{OLVCMOS18\_F12}$	0.26	0.27	0.30	ns
LVCMOS, 1.8V, Fast, 16 mA	LVCMOS18_F16	$T_{OLVCMOS18\_F16}$	0.23	0.23	0.26	ns
LVCMOS, 1.5V, Slow, 2 mA	LVCMOS15_S2	$T_{OLVCMOS15\_S2}$	18.96	19.55	21.50	ns
LVCMOS, 1.5V, Slow, 4 mA	LVCMOS15_S4	$T_{OLVCMOS15\_S4}$	12.77	13.17	14.48	ns
LVCMOS, 1.5V, Slow, 6 mA	LVCMOS15_S6	$T_{OLVCMOS15\_S6}$	12.05	12.42	13.66	ns
LVCMOS, 1.5V, Slow, 8 mA	LVCMOS15_S8	$T_{OLVCMOS15\_S8}$	9.75	10.06	11.06	ns
LVCMOS, 1.5V, Slow, 12 mA	LVCMOS15_S12	$T_{OLVCMOS15\_S12}$	9.04	9.32	10.25	ns
LVCMOS, 1.5V, Slow, 16 mA	LVCMOS15_S16	$T_{OLVCMOS15\_S16}$	8.21	8.46	9.31	ns
LVCMOS, 1.5V, Fast, 2 mA	LVCMOS15_F2	$T_{OLVCMOS15\_F2}$	5.09	5.25	5.78	ns
LVCMOS, 1.5V, Fast, 4 mA	LVCMOS15_F4	$T_{OLVCMOS15\_F4}$	2.01	2.07	2.27	ns
LVCMOS, 1.5V, Fast, 6 mA	LVCMOS15_F6	$T_{OLVCMOS15\_F6}$	1.46	1.51	1.66	ns
LVCMOS, 1.5V, Fast, 8 mA	LVCMOS15_F8	$T_{OLVCMOS15\_F8}$	0.93	0.96	1.05	ns
LVCMOS, 1.5V, Fast, 12 mA	LVCMOS15_F12	$T_{OLVCMOS15\_F12}$	0.74	0.77	0.84	ns
LVCMOS, 1.5V, Fast, 16 mA	LVCMOS15_F16	$T_{OLVCMOS15\_F16}$	0.67	0.69	0.75	ns
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	T_{OLVDS_25}	–0.31	–0.32	–0.36	ns
LVDS, 3.3V	LVDS_33	T_{OLVDS_33}	–0.25	–0.26	–0.29	ns
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	$T_{OLVDSEXT\_25}$	–0.18	–0.19	–0.21	ns
LVDSEXT, 3.3V	LVDSEXT_33	$T_{OLVDSEXT\_33}$	–0.17	–0.18	–0.19	ns
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	T_{OULVDS_25}	–0.20	–0.21	–0.23	ns
BLVDS (Bus LVDS), 2.5V	BLVDS_25	T_{OBLVDS_25}	0.67	0.69	0.76	ns
LDT (HyperTransport), 2.5V	LDT_25	T_{OLDT_25}	–0.20	–0.21	–0.23	ns
LVPECL (Low-Voltage Positive Electron-Coupled Logic), 3.3V	LVPECL_33	$T_{OLVPECL\_33}$	0.29	0.30	0.33	ns
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	T_{OPCI33_3}	1.15	1.19	1.31	ns
PCI, 66 MHz, 3.3V	PCI66_3	T_{OPCI66_3}	–0.01	–0.01	–0.01	ns
PCI-X, 133 MHz, 3.3V	PCIX	T_{OPCIX}	–0.01	–0.01	–0.01	ns
GTL (Gunning Transceiver Logic)	GTL	T_{OGTL}	–0.31	–0.32	–0.36	ns
GTL Plus	GTLP	T_{OGTLP}	–0.17	–0.18	–0.20	ns
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	T_{OHSTL_I}	0.26	0.27	0.29	ns
HSTL, Class II	HSTL_II	T_{OHSTL_II}	–0.15	–0.16	–0.17	ns
HSTL, Class III	HSTL_III	T_{OHSTL_III}	–0.17	–0.17	–0.19	ns
HSTL, Class IV	HSTL_IV	T_{OHSTL_IV}	–0.40	–0.41	–0.45	ns
HSTL, Class I, 1.8V	HSTL_I_18	$T_{OHSTL\_I\_18}$	0.03	0.03	0.04	ns

Configuration Timing

Configuration Memory Clearing Parameters

Power-up timing of configuration signals is shown in Figure 2; corresponding timing characteristics are listed in Table 30.

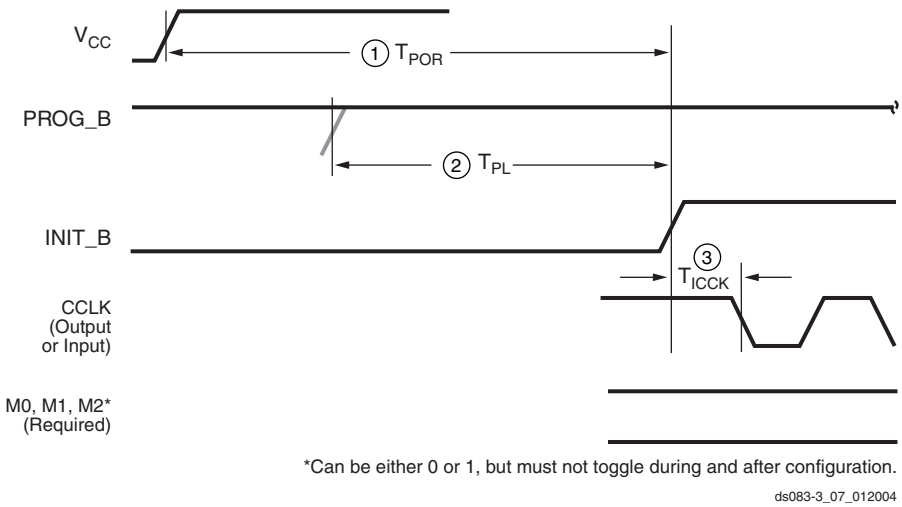


Figure 2: **Configuration Power-Up Timing**

Table 30: **Power-Up Timing Characteristics**

Description	Figure References	Symbol	Value	Units
Power-on reset	1	T_{POR}	T_{PL} + 2	ms, max
Program latency	2	T_{PL}	4	µs per frame, max
CCLK (output) delay	3	T_{ICCK}	0.5	µs, min
			4.0	µs, max
Program pulse width		$T_{PROGRAM}$	300	ns, min

Notes:
1. The M2, M1, and M0 mode pins should be set at a constant DC voltage level, either through pull-up or pull-down resistors, or tied directly to ground or V_{CCAUX}. The mode pins should not be toggled during and after configuration.

Master/Slave Serial Mode Parameters

Clock timing for Slave Serial configuration programming is shown in Figure 3, with Master Serial clock timing shown in Figure 4. Programming parameters for both Slave and Master modes are given in Table 31.

DCM Timing Parameters

All devices are 100% functionally tested. Because of the difficulty in directly measuring many internal timing parameters, those parameters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions. All output jitter and phase specifications are determined through statistical measurement at the package pins.

Operating Frequency Ranges

Table 38: **Operating Frequency Ranges**

Description	Symbol	Constraints	Speed Grade			Units
			-6	-5	-4	
Output Clocks (Low Frequency Mode)						
CLK0, CLK90, CLK180, CLK270	CLKOUT_FREQ_1X_LF_Min		24.00	24.00	24.00	MHz
	CLKOUT_FREQ_1X_LF_Max		230.00	210.00	180.00	MHz
CLK2X, CLK2X180	CLKOUT_FREQ_2X_LF_Min		48.00	48.00	48.00	MHz
	CLKOUT_FREQ_2X_LF_Max		450.00	420.00	360.00	MHz
CLKDV	CLKOUT_FREQ_DV_LF_Min		1.50	1.50	1.50	MHz
	CLKOUT_FREQ_DV_LF_Max		150.00	140.00	120.00	MHz
CLKFX, CLKFX180	CLKOUT_FREQ_FX_LF_Min		24.00	24.00	24.00	MHz
	CLKOUT_FREQ_FX_LF_Max		260.00	240.00	210.00	MHz
Input Clocks (Low Frequency Mode)						
CLKIN (using DLL outputs) (1,3,4)	CLKIN_FREQ_DLL_LF_Min		24.00	24.00	24.00	MHz
	CLKIN_FREQ_DLL_LF_Max		230.00	210.00	180.00	MHz
CLKIN (using CLKFX outputs) (2,3,4)	CLKIN_FREQ_FX_LF_Min		1.00	1.00	1.00	MHz
	CLKIN_FREQ_FX_LF_Max		260.00	240.00	210.00	MHz
PSCLK	PSCLK_FREQ_LF_Min		0.01	0.01	0.01	MHz
	PSCLK_FREQ_LF_Max		450.00	420.00	360.00	MHz
Output Clocks (High Frequency Mode)						
CLK0, CLK180	CLKOUT_FREQ_1X_HF_Min		48.00	48.00	48.00	MHz
	CLKOUT_FREQ_1X_HF_Max		450.00	420.00	360.00	MHz
CLKDV	CLKOUT_FREQ_DV_HF_Min		3.00	3.00	3.00	MHz
	CLKOUT_FREQ_DV_HF_Max		300.00	280.00	240.00	MHz
CLKFX, CLKFX180	CLKOUT_FREQ_FX_HF_Min		210.00	210.00	210.00	MHz
	CLKOUT_FREQ_FX_HF_Max		350.00	320.00	270.00	MHz
Input Clocks (High Frequency Mode)						
CLKIN (using DLL outputs) (1,3,4)	CLKIN_FREQ_DLL_HF_Min		48.00	48.00	48.00	MHz
	CLKIN_FREQ_DLL_HF_Max		450.00	420.00	360.00	MHz
CLKIN (using CLKFX outputs) (2,3,4)	CLKIN_FRQ_FX_HF_Min		50.00	50.00	50.00	MHz
	CLKIN_FRQ_FX_HF_Max		350.00	320.00	270.00	MHz
PSCLK	PSCLK_FREQ_HF_Min		0.01	0.01	0.01	MHz
	PSCLK_FREQ_HF_Max		450.00	420.00	360.00	MHz

Notes:
1. "DLL outputs" is used here to describe the outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV.
2. If both DLL and CLKFX outputs are used, follow the more restrictive specification.
3. If the CLKIN_DIVIDE_BY_2 attribute of the DCM is used, then double these values.
4. If the CLKIN_DIVIDE_BY_2 attribute of the DCM is used and CLKIN frequency > 400 MHz, CLKIN duty cycle must be within ±5% (45/55 to 55/45).

Table 6: **FG256/FGG256 BGA — XC2V40, XC2V80, XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V40	No Connect in XC2V80
5	IO_L01P_5/CS_B	T3		
6	IO_L01P_6	P1		
6	IO_L01N_6	N1		
6	IO_L02P_6/VRN_6	N3		
6	IO_L02N_6/VRP_6	N2		
6	IO_L03P_6	M4		
6	IO_L03N_6/VREF_6	M3		
6	IO_L04P_6	M2	NC	
6	IO_L04N_6	M1	NC	
6	IO_L06P_6	L4	NC	
6	IO_L06N_6	L3	NC	
6	IO_L43P_6	L2	NC	NC
6	IO_L43N_6	L1	NC	NC
6	IO_L45P_6	L5	NC	NC
6	IO_L45N_6/VREF_6	K5	NC	NC
6	IO_L91P_6	K4	NC	
6	IO_L91N_6	K3	NC	
6	IO_L93P_6	K2	NC	
6	IO_L93N_6/VREF_6	K1	NC	
6	IO_L94P_6	J4		
6	IO_L94N_6	J3		
6	IO_L96P_6	J2		
6	IO_L96N_6	J1		
7	IO_L96P_7	H1		
7	IO_L96N_7	H2		
7	IO_L94P_7	H3		
7	IO_L94N_7	H4		
7	IO_L93P_7/VREF_7	G1	NC	
7	IO_L93N_7	G2	NC	
7	IO_L91P_7	G3	NC	
7	IO_L91N_7	G4	NC	
7	IO_L45P_7/VREF_7	G5	NC	NC

Table 7: **FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
1	IO_L21P_1	D16	NC	NC
1	IO_L06N_1	E16		
1	IO_L06P_1	E17		
1	IO_L05N_1	A17		
1	IO_L05P_1	B17		
1	IO_L04N_1	C17		
1	IO_L04P_1/VREF_1	D17		
1	IO_L03N_1/VRP_1	A18		
1	IO_L03P_1/VRN_1	B18		
1	IO_L02N_1	C18		
1	IO_L02P_1	D18		
1	IO_L01N_1	A19		
1	IO_L01P_1	B19		
2	IO_L01N_2	C21		
2	IO_L01P_2	C22		
2	IO_L02N_2/VRP_2	E18		
2	IO_L02P_2/VRN_2	F18		
2	IO_L03N_2	D21		
2	IO_L03P_2/VREF_2	D22		
2	IO_L04N_2	E19		
2	IO_L04P_2	E20		
2	IO_L06N_2	E21		
2	IO_L06P_2	E22		
2	IO_L19N_2	F19	NC	NC
2	IO_L19P_2	F20	NC	NC
2	IO_L21N_2	F21	NC	NC
2	IO_L21P_2/VREF_2	F22	NC	NC
2	IO_L22N_2	G18	NC	NC
2	IO_L22P_2	H18	NC	NC
2	IO_L24N_2	G19	NC	NC
2	IO_L24P_2	G20	NC	NC
2	IO_L43N_2	G21		
2	IO_L43P_2	G22		

Table 7: **FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000**

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
6	IO_L46P_6	R2		
6	IO_L46N_6	R1		
6	IO_L48P_6	P6		
6	IO_L48N_6	P5		
6	IO_L49P_6	P4	NC	
6	IO_L49N_6	P3	NC	
6	IO_L51P_6	P2	NC	
6	IO_L51N_6/VREF_6	P1	NC	
6	IO_L52P_6	N6	NC	
6	IO_L52N_6	N5	NC	
6	IO_L54P_6	N4	NC	
6	IO_L54N_6	N3	NC	
6	IO_L91P_6	N2		
6	IO_L91N_6	N1		
6	IO_L93P_6	M6		
6	IO_L93N_6/VREF_6	M5		
6	IO_L94P_6	M4		
6	IO_L94N_6	M3		
6	IO_L96P_6	M2		
6	IO_L96N_6	M1		
7	IO_L96P_7	L2		
7	IO_L96N_7	L3		
7	IO_L94P_7	L4		
7	IO_L94N_7	L5		
7	IO_L93P_7/VREF_7	K1		
7	IO_L93N_7	K2		
7	IO_L91P_7	K3		
7	IO_L91N_7	K4		
7	IO_L54P_7	L6	NC	
7	IO_L54N_7	K6	NC	
7	IO_L52P_7	K5	NC	
7	IO_L52N_7	J5	NC	
7	IO_L51P_7/VREF_7	J1	NC	

FG676/FGG676 Fine-Pitch BGA Package

As shown in Table 8, XC2V1500, XC2V2000, and XC2V3000 Virtex-II devices are available in the FG676/FGG676 fine-pitch BGA package. Pins in the XC2V1500, XC2V2000, and XC2V3000 devices are the same, except for the pin differences in the XC2V1500 and XC2V2000 devices shown in the No Connect columns. Following this table are the FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 8: **FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000**

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
0	IO_L01N_0	D6		
0	IO_L01P_0	C6		
0	IO_L02N_0	B1		
0	IO_L02P_0	A2		
0	IO_L03N_0/VRP_0	D7		
0	IO_L03P_0/VRN_0	C7		
0	IO_L04N_0/VREF_0	B3		
0	IO_L04P_0	A3		
0	IO_L05N_0	G6		
0	IO_L05P_0	G7		
0	IO_L06N_0	E6		
0	IO_L06P_0	E7		
0	IO_L19N_0	B4		
0	IO_L19P_0	A4		
0	IO_L21N_0	B5		
0	IO_L21P_0/VREF_0	A5		
0	IO_L22N_0	B6		
0	IO_L22P_0	A6		
0	IO_L24N_0	A7		
0	IO_L24P_0	A8		
0	IO_L25N_0	E8	NC	NC
0	IO_L25P_0	D8	NC	NC
0	IO_L27N_0	G8	NC	NC
0	IO_L27P_0/VREF_0	F8	NC	NC
0	IO_L49N_0	C8		
0	IO_L49P_0	B8		
0	IO_L51N_0	D9		
0	IO_L51P_0/VREF_0	E9		
0	IO_L52N_0	F9		
0	IO_L52P_0	G9		
0	IO_L54N_0	B9		
0	IO_L54P_0	A9		
0	IO_L67N_0	C9		

Table 9: **BG575/BGG575 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in XC2V1000	No Connect in XC2V1500
2	IO_L01P_2	D23		
2	IO_L02N_2/VRP_2	E21		
2	IO_L02P_2/VRN_2	E22		
2	IO_L03N_2	F21		
2	IO_L03P_2/VREF_2	F20		
2	IO_L04N_2	G20		
2	IO_L04P_2	G19		
2	IO_L06N_2	H18		
2	IO_L06P_2	J17		
2	IO_L19N_2	D24		
2	IO_L19P_2	E23		
2	IO_L21N_2	E24		
2	IO_L21P_2/VREF_2	F24		
2	IO_L22N_2	F23		
2	IO_L22P_2	G23		
2	IO_L24N_2	G21		
2	IO_L24P_2	G22		
2	IO_L43N_2	H19		
2	IO_L43P_2	H20		
2	IO_L45N_2	J18		
2	IO_L45P_2/VREF_2	J19		
2	IO_L46N_2	K17		
2	IO_L46P_2	K18		
2	IO_L48N_2	H23		
2	IO_L48P_2	H24		
2	IO_L49N_2	H21		
2	IO_L49P_2	H22		
2	IO_L51N_2	J24		
2	IO_L51P_2/VREF_2	K24		
2	IO_L52N_2	J22		
2	IO_L52P_2	J23		
2	IO_L54N_2	J20		
2	IO_L54P_2	J21		
2	IO_L67N_2	K19	NC	
2	IO_L67P_2	K20	NC	
2	IO_L69N_2	L17	NC	

Table 9: **BG575/BGG575 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in XC2V1000	No Connect in XC2V1500
NA	GND	Y5		
NA	GND	W19		
NA	GND	W6		
NA	GND	V24		
NA	GND	V18		
NA	GND	V7		
NA	GND	V1		
NA	GND	R21		
NA	GND	R4		
NA	GND	P14		
NA	GND	P13		
NA	GND	P12		
NA	GND	P11		
NA	GND	N14		
NA	GND	N13		
NA	GND	N12		
NA	GND	N11		
NA	GND	M14		
NA	GND	M13		
NA	GND	M12		
NA	GND	M11		
NA	GND	L14		
NA	GND	L13		
NA	GND	L12		
NA	GND	L11		
NA	GND	K21		
NA	GND	K4		
NA	GND	G24		
NA	GND	G18		
NA	GND	G7		
NA	GND	G1		
NA	GND	F19		
NA	GND	F6		
NA	GND	E20		
NA	GND	E5		
NA	GND	D21		

Table 11: **FF896 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
1	IO_L68P_1	G12	NC	
1	IO_L67N_1	A9	NC	
1	IO_L67P_1	A10	NC	
1	IO_L54N_1	E10		
1	IO_L54P_1	E11		
1	IO_L53N_1	H12		
1	IO_L53P_1	H11		
1	IO_L52N_1	D9		
1	IO_L52P_1	D10		
1	IO_L51N_1/VREF_1	C9		
1	IO_L51P_1	C8		
1	IO_L50N_1	F11		
1	IO_L50P_1	F10		
1	IO_L49N_1	B8		
1	IO_L49P_1	B9		
1	IO_L24N_1	E8		
1	IO_L24P_1	E9		
1	IO_L23N_1	G11		
1	IO_L23P_1	H10		
1	IO_L22N_1	B7		
1	IO_L22P_1	A7		
1	IO_L21N_1/VREF_1	D8		
1	IO_L21P_1	E7		
1	IO_L20N_1	G10		
1	IO_L20P_1	G9		
1	IO_L19N_1	A5		
1	IO_L19P_1	A6		
1	IO_L06N_1	C6		
1	IO_L06P_1	C7		
1	IO_L05N_1	F9		
1	IO_L05P_1	G8		
1	IO_L04N_1	B6		
1	IO_L04P_1/VREF_1	C5		
1	IO_L03N_1/VRP_1	D7		
1	IO_L03P_1/VRN_1	D6		
1	IO_L02N_1	F8		
1	IO_L02P_1	F7		

Table 11: **FF896 BGA — XC2V1000, XC2V1500, and XC2V2000**

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
NA	GND	AC1		
NA	GND	AA28		
NA	GND	AA3		
NA	GND	W26		
NA	GND	W19		
NA	GND	W18		
NA	GND	W17		
NA	GND	W16		
NA	GND	W15		
NA	GND	W14		
NA	GND	W13		
NA	GND	W12		
NA	GND	W5		
NA	GND	V19		
NA	GND	V18		
NA	GND	V17		
NA	GND	V16		
NA	GND	V15		
NA	GND	V14		
NA	GND	V13		
NA	GND	V12		
NA	GND	U24		
NA	GND	U19		
NA	GND	U18		
NA	GND	U17		
NA	GND	U16		
NA	GND	U15		
NA	GND	U14		
NA	GND	U13		
NA	GND	U12		
NA	GND	U7		
NA	GND	T19		
NA	GND	T18		
NA	GND	T17		
NA	GND	T16		
NA	GND	T15		
NA	GND	T14		

Table 12: **FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
2	IO_L21N_2	H7	
2	IO_L21P_2/VREF_2	J7	
2	IO_L22N_2	H6	
2	IO_L22P_2	G6	
2	IO_L23N_2	L10	
2	IO_L23P_2	L9	
2	IO_L24N_2	G3	
2	IO_L24P_2	F3	
2	IO_L25N_2	G2	
2	IO_L25P_2	F2	
2	IO_L26N_2	M10	
2	IO_L26P_2	N10	
2	IO_L27N_2	J6	
2	IO_L27P_2/VREF_2	K6	
2	IO_L28N_2	J5	
2	IO_L28P_2	H5	
2	IO_L29N_2	L7	
2	IO_L29P_2	K7	
2	IO_L30N_2	J4	
2	IO_L30P_2	H4	
2	IO_L43N_2	G1	
2	IO_L43P_2	F1	
2	IO_L44N_2	L8	
2	IO_L44P_2	M8	
2	IO_L45N_2	J1	
2	IO_L45P_2/VREF_2	H2	
2	IO_L46N_2	J3	
2	IO_L46P_2	H3	
2	IO_L47N_2	M9	
2	IO_L47P_2	N9	
2	IO_L48N_2	L5	
2	IO_L48P_2	K5	
2	IO_L49N_2	K2	
2	IO_L49P_2	J2	
2	IO_L50N_2	N7	
2	IO_L50P_2	M7	

Table 12: **FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
NA	VCCINT	AB17	
NA	VCCINT	AB16	
NA	VCCINT	AB15	
NA	VCCINT	AB14	
NA	VCCINT	AB13	
NA	VCCINT	AA22	
NA	VCCINT	AA13	
NA	VCCINT	Y22	
NA	VCCINT	Y13	
NA	VCCINT	W22	
NA	VCCINT	W13	
NA	VCCINT	V22	
NA	VCCINT	V13	
NA	VCCINT	U22	
NA	VCCINT	U13	
NA	VCCINT	T22	
NA	VCCINT	T13	
NA	VCCINT	R22	
NA	VCCINT	R13	
NA	VCCINT	P22	
NA	VCCINT	P13	
NA	VCCINT	N22	
NA	VCCINT	N21	
NA	VCCINT	N20	
NA	VCCINT	N19	
NA	VCCINT	N18	
NA	VCCINT	N17	
NA	VCCINT	N16	
NA	VCCINT	N15	
NA	VCCINT	N14	
NA	VCCINT	N13	
NA	VCCINT	M23	
NA	VCCINT	M12	
NA	VCCINT	L24	
NA	VCCINT	L11	

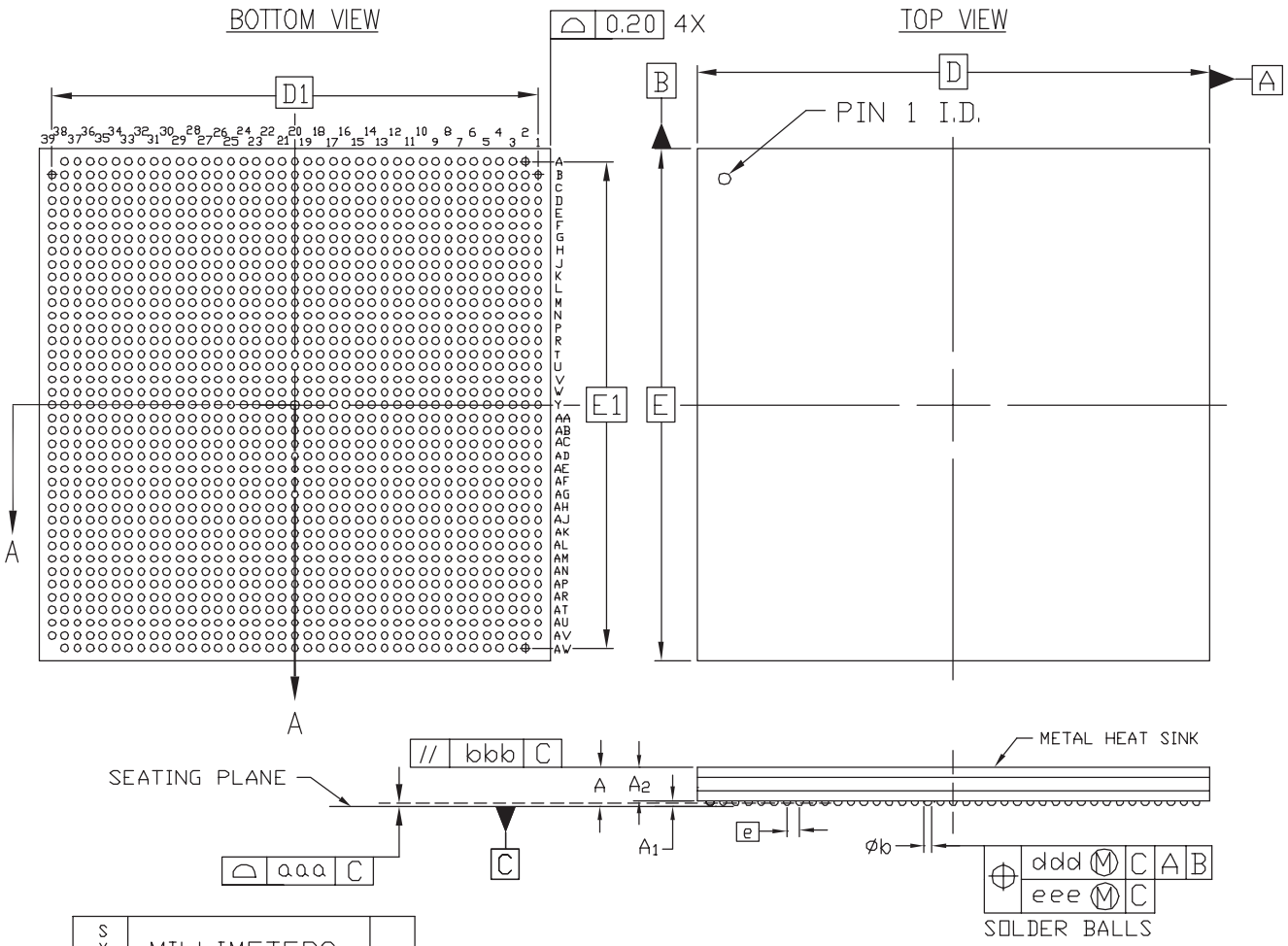
Table 13: **FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
6	IO_L71N_6	AE39		
6	IO_L72P_6	AD36		
6	IO_L72N_6	AE36		
6	IO_L73P_6	AB29		
6	IO_L73N_6	AA29		
6	IO_L74P_6	AE38		
6	IO_L74N_6	AD38		
6	IO_L75P_6	AC33		
6	IO_L75N_6/VREF_6	AD33		
6	IO_L76P_6	AB30		
6	IO_L76N_6	AA30		
6	IO_L77P_6	AD37		
6	IO_L77N_6	AC37		
6	IO_L78P_6	AB34		
6	IO_L78N_6	AC34		
6	IO_L79P_6	AB31		
6	IO_L79N_6	AA31		
6	IO_L80P_6	AD39		
6	IO_L80N_6	AC39		
6	IO_L81P_6	AB35		
6	IO_L81N_6/VREF_6	AC35		
6	IO_L82P_6	AB32		
6	IO_L82N_6	AA32		
6	IO_L83P_6	AC38		
6	IO_L83N_6	AB38		
6	IO_L84P_6	AA33		
6	IO_L84N_6	AB33		
6	IO_L91P_6	Y28		
6	IO_L91N_6	Y29		
6	IO_L92P_6	AB39		
6	IO_L92N_6	AA39		
6	IO_L93P_6	AA36		
6	IO_L93N_6/VREF_6	AB36		
6	IO_L94P_6	Y31		
6	IO_L94N_6	Y32		
6	IO_L95P_6	AA37		

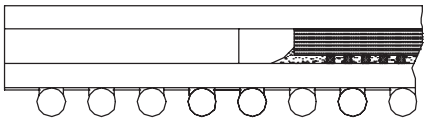
Table 13: **FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000**

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
7	IO_L50P_7	P32		
7	IO_L50N_7	N32		
7	IO_L49P_7	L37		
7	IO_L49N_7	M37		
7	IO_L48P_7	N34		
7	IO_L48N_7	P34		
7	IO_L47P_7	P31		
7	IO_L47N_7	N31		
7	IO_L46P_7	M35		
7	IO_L46N_7	N35		
7	IO_L45P_7/VREF_7	L36		
7	IO_L45N_7	M36		
7	IO_L44P_7	R28		
7	IO_L44N_7	P28		
7	IO_L43P_7	K39		
7	IO_L43N_7	L39		
7	IO_L36P_7	L34	NC	
7	IO_L36N_7	M34	NC	
7	IO_L35P_7	P29	NC	
7	IO_L35N_7	N29	NC	
7	IO_L34P_7	J38	NC	
7	IO_L34N_7	K38	NC	
7	IO_L33P_7/VREF_7	L33	NC	
7	IO_L33N_7	M33	NC	
7	IO_L32P_7	M32	NC	
7	IO_L32N_7	L32	NC	
7	IO_L31P_7	H39	NC	
7	IO_L31N_7	J39	NC	
7	IO_L30P_7	J36		
7	IO_L30N_7	K36		
7	IO_L29P_7	N30		
7	IO_L29N_7	M30		
7	IO_L28P_7	J37		
7	IO_L28N_7	K37		
7	IO_L27P_7/VREF_7	J35		
7	IO_L27N_7	K35		

FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A		3.20	3.40	
A_1	0.40	0.50	0.60	
A_2			2.80	
D/E	40.00 BASIC			
D_1/E_1	38.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
bbb			0.25	
ddd			0.25	
eee			0.10	
M		39		2



SECTION A–A
(NOT TO SCALE)

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M–1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–AAU–1 (DEPOPULATED)

Figure 9: **FF1517 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 14: **BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000**

Bank	Pin Description	Pin Number	No Connect in XC2V2000
NA	GND	T14	
NA	GND	T15	
NA	GND	T16	
NA	GND	T17	
NA	GND	T18	
NA	GND	T22	
NA	GND	T25	
NA	GND	T28	
NA	GND	T31	
NA	GND	U14	
NA	GND	U15	
NA	GND	U16	
NA	GND	U17	
NA	GND	U18	
NA	GND	V14	
NA	GND	V15	
NA	GND	V16	
NA	GND	V17	
NA	GND	V18	
NA	GND	W7	
NA	GND	W25	
NA	GND	AB4	
NA	GND	AB16	
NA	GND	AB28	
NA	GND	AC9	
NA	GND	AC23	
NA	GND	AD2	
NA	GND	AD8	
NA	GND	AD24	
NA	GND	AD30	
NA	GND	AE7	
NA	GND	AE13	
NA	GND	AE16	
NA	GND	AE19	
NA	GND	AE25	
NA	GND	AF6	
NA	GND	AF26	
NA	GND	AG5	